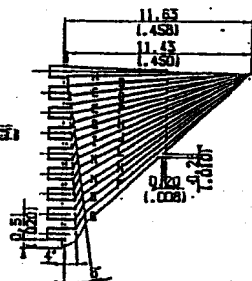


SSM P/N CQJ06808

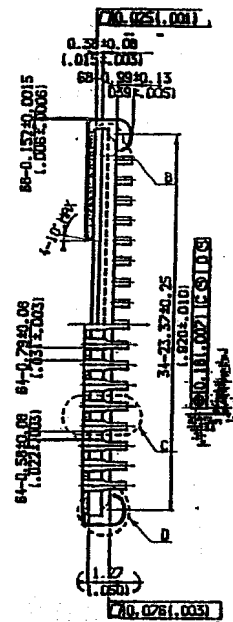
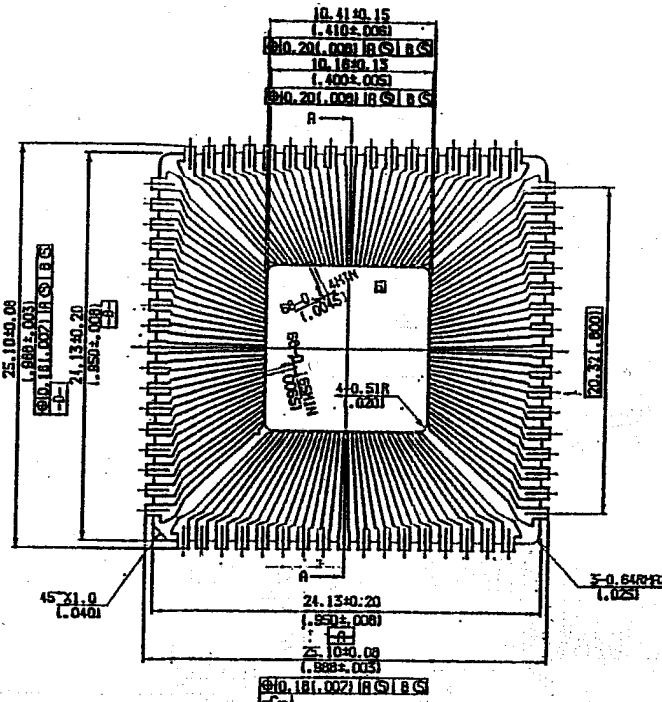
NOTES

1. FRG16 CERAMIC TO SPEC. 50-847 PL20; SOLDER GLASS TO BE 7583; MAX FILLBACK TO BE 0.251(.010) FROM CERAMIC EDGE. GATE ATTACH AREA TO BE A .120 MICRONS MIN. LEAD FRAME TO BE ALLOY 42. TYPE B MIL 38510 PARAGRAPH 3.5.5.1 WITH ALUMINUM BOND PROS. 100MICRONS THICK AND 35 MILS IN LENGTH WITH NO SILL-BRIDGES.
2. THERE WILL BE NO UNSUPPORTED BOND PROS GREATER THAN 0.251(.010)
3. ADJACENT BOND PROS MUST BE CO-PLANAR WITHIN 0.151(.005). TOTAL CO-PLANARITY NO GREATER THAN 0.251(.010)
4. THERE WILL BE NO KICKS, CUTS OR GLASS IN THE BOND PROS
5. MINIMUM INTERNAL METAL SEPARATION, OTHER THAN BOND FINGERS, TO BE 0.131(.005)

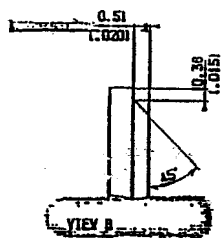
A	1.45
B	1.37
C	2.27
D	10.15
E	17.98
F	15.80
G	18.57
H	21.78
I	28.57
J	28.57
K	28.12
L	31.60
M	32.05
N	38.57
P	40.87
Q	43.00



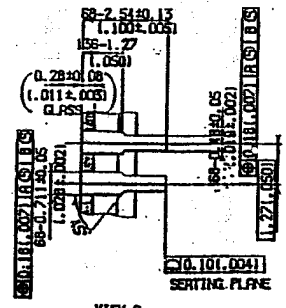
LEAD TIP DETAIL



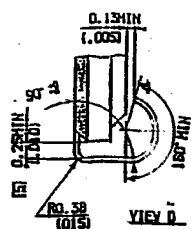
SECTION A-A



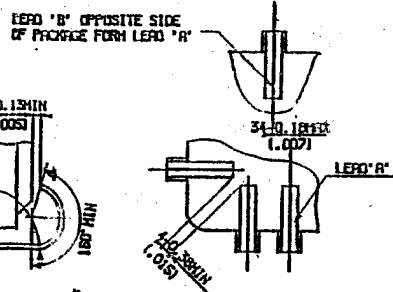
VIEW B



VIEW C



VIEW D



JEDEC TYPE

NAME 68LD QUAD CERPAC™ J (850-400)	TOLERANCES UNLESS OTHERWISE SPECIFIED	BRAND Kyocera	DATE 8.1
SCALE 5:1	REVISION	DESIGNED BY JAN 15	
KYOCERA CORPORATION KYOTO JAPAN		QC-068271-J	

